L Number	Hits	Search Text	DB	Time stamp
1	1	(semiconductor or semiconductive) and	USPAT;	2004/02/20 11:40
		(organic with (insulat\$4 or dielectric)) and	US-PGPUB;	, , == == : 3
		ethyne and (UV same (heat or heating or	EPO; JPO;	
		heated or anneal or annealing or annealed or	DERWENT;	
•		bake or baking or baked))	IBM_TDB	
2	24		USPAT;	2004/02/20 11:41
		(organic with (insulat\$4 or dielectric)) and	US-PGPUB;	
		SILK and (UV same (heat or heating or heated	EPO; JPO;	
		or anneal or annealing or annealed or bake	DERWENT;	
_		or baking or baked))	IBM_TDB	1
3	3	1 (USPAT;	2004/02/20 11:46
[(organic with (insulat\$4 or dielectric)) and	US-PGPUB;	
		SILK and (UV same (heat or heating or heated	EPO; JPO;	
		or anneal or annealing or annealed or bake	DERWENT;	
		or baking or baked) same polymeriz\$5)	IBM_TDB	0001/05/55
4	64	(semiconductor or semiconductive) and	USPAT;	2004/02/20 13:10
j l	ļ .	(organic with (insulat\$4 or dielectric)) and	US-PGPUB;	
		(UV same (heat or heating or heated or	EPO; JPO;	
		anneal or annealing or annealed or bake or	DERWENT;	
		baking or baked) same polymeriz\$5)	IBM_TDB	2004/02/22 ==
5	45	, ,	USPAT;	2004/02/20 11:47
		(organic with (insulat\$4 or dielectric)) and	US-PGPUB;	
	ļ	(UV same (heat or heating or heated or anneal or annealing or annealed or bake or	EPO; JPO;	
		baking or baked) same polymeriz\$5)) and	DERWENT;]
		(monomer or oligomer)	IBM_TDB	
6	6	(monomer or oligomer) ((thin adj film) or TFT) and (organic with	USPAT;	2004/02/20 13:09
_	"	((thin ad) film) or TFT) and (organic with (insulat\$4 or dielectric)) and (UV same	USPAT; US-PGPUB;	
	[(heat or heating or heated or anneal or	EPO; JPO;	
	<u> </u>	annealing or annealed or bake or baking or	DERWENT;	
	ļ .	baked) same polymeriz\$5) and (SILK or	IBM TDB	
	ļ .	"GX-3")		
7	9	(organic with (insulat\$4 or dielectric)) and	USPAT;	2004/02/20 13:10
	[(UV same (heat or heating or heated or	US-PGPUB;	
		anneal or annealing or annealed or bake or	EPO; JPO;	
		baking or baked) same polymeriz\$5) and (SILK	DERWENT;	
		or "GX-3")	IBM_TDB	
8	3	((organic with (insulat\$4 or dielectric))	USPAT;	2004/02/20 13:09
	ļ Ì	and (UV same (heat or heating or heated or	US-PGPUB;	
		anneal or annealing or annealed or bake or	EPO; JPO;	
		baking or baked) same polymeriz\$5) and (SILK	DERWENT;	
	1	or "GX-3")) not (((thin adj film) or TFT)	IBM_TDB	
	!	and (organic with (insulat\$4 or dielectric))	ļ .	
	1	and (UV same (heat or heating or heated or	ļ	
	1	anneal or annealing or annealed or bake or		
	1 j	baking or baked) same polymeriz\$5) and (SILK		
9	ا م	or "GX-3"))	IIODAM -	2004/02/20 12 15
1	62	<pre>(organic with (insulat\$4 or dielectric)) and (UV and (heat or heating or heated or anneal</pre>	USPAT;	2004/02/20 13:12
	1	or anno (heat or heating or heated or anneal or anneal or anneal or anneal or baking	US-PGPUB;	
}	\	or annealing or annealed or bake or baking or baked) and polymeriz\$5) and (SILK or	EPO; JPO;	
	1	"GX-3")	DERWENT; IBM TDB	
10	24	((organic with (insulat\$4 or dielectric))	USPAT;	2004/02/20 13:19
	23	and (UV and (heat or heating or heated or	US-PGPUB;	
	1	anneal or annealing or annealed or bake or	EPO; JPO;	
	1	baking or baked) and polymeriz\$5) and (SILK	DERWENT;	
	1	or "GX-3")) not (silk adj screen\$4)	IBM TDB	
11	2510	((438/758) or (438/780-781) or	USPAT;	2004/02/20 16:09
	1	(438/789-790)).CCLS.	US-PGPUB;	,
			EPO; JPO;	
1	1		DERWENT;	
	1		IBM_TDB	
12	53	(((438/758) or (438/780-781) or	USPAT;	2004/02/20 13:25
ļ		(438/789-790)).CCLS.) and (SILK or "GX-3")	US-PGPUB;	
İ			EPO; JPO;	
	'		DERWENT;	
			IBM_TDB	1

13	2	((((438/758) or (438/780-781) or (438/789-790)).CCLS.) and (SILK or "GX-3"))	USPAT; US-PGPUB;	2004/02/20 13:26
		and ((UV or ultraviolet) with polymeriz\$6)	EPO; JPO; DERWENT;	
	1		IBM_TDB	
14	8	(((438/758) or (438/780-781) or	USPAT;	2004/02/20 14:37
		(438/789-790)).CCLS.) and (organic with	US-PGPUB; EPO; JPO;	
		(insulat\$4 or dielectric)) and ((UV or ultraviolet) with polymeriz\$6)	DERWENT;	
		dictaviolet, with polymerizato,	IBM TDB	
15	42	(UV or ultraviolet) with (heat or heating or	USPAT;	2004/02/20 14:38
		cure or curing or anneal or annealing or	US-PGPUB;	
1		bake or baking) with polymer\$8 with (low adj	EPO; JPO;	
		temperature)	DERWENT;	
16	0	//ITI or ultraviolat) with /heat or heating	IBM_TDB	2004/02/20 14:39
16	"	((UV or ultraviolet) with (heat or heating or cure or curing or anneal or annealing or	USPAT; US-PGPUB;	2004/02/20 14:39
1		bake or baking) with polymer\$8 with (low adj	EPO; JPO;	
		temperature)) and (SILK) not (silk adj	DERWENT;	
1		screen\$4)	IBM_TDB	
17	· 0	((UV or ultraviolet) with (heat or heating	USPAT;	2004/02/20 14:39
		or cure or curing or anneal or annealing or	US-PGPUB;	
		bake or baking) with polymer\$8 with (low adj	EPO; JPO; DERWENT;	
		temperature)) and (organic with (insultatis4 or dielectric))	TBM TDB	
18	2	((UV or ultraviolet) with (heat or heating	USPAT;	2004/02/20 15:06
		or cure or curing or anneal or annealing or	US-PGPUB;	
		bake or baking) with polymer\$8 with (low adj	EPO; JPO;	
		temperature)) and (organic with precursor)	DERWENT;	
10	6540	(420 (140 166) 9979	IBM_TDB	2004/02/20 15 07
19	6548	(438/149-166).CCLS.	USPAT; US-PGPUB;	2004/02/20 15:07
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
20	41		USPAT;	2004/02/20 15:09
		substrate) and matrix.ti. and (gate with	US-PGPUB;	
		line) and electrode\$1 and (source with line) and (source with electrode\$1) and (pixel	EPO; JPO; DERWENT;	
		with electrodes)	IBM TDB	
21	9	(((438/149-166).CCLS.) and (transparent with	USPAT;	2004/02/20 15:09
		substrate) and matrix.ti. and (gate with	US-PGPUB;	
		line) and electrode\$1 and (source with line)	EPO; JPO;	
		and (source with electrode\$1) and (pixel	DERWENT;	
		with electrodes)) and (organic with	IBM_TDB	
22	2	(dielectric or insulati\$4)) ("4756977").PN.	USPAT;	2004/02/20 16:10
		1,000// /	US-PGPUB;	2003/02/20 10.10
			EPO; JPO;	
			DERWENT;	
			IBM TDB	